



## Material Content Data Sheet



<b>Sales Product Name</b>		BFR 380F H6327		<b>Issued</b>		20. July 2018			
<b>MA#</b>		MA000895444							
<b>Package</b>		PG-TSFP-3-1		<b>Weight*</b>		1.43 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.000	0.03		324		
	noble metal	gold	7440-57-5	0.002	0.13		1258		
	inorganic material	silicon	7440-21-3	0.013	0.93	1.09	9323	10905	
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		80		
	non noble metal	titanium	7440-32-6	0.001	0.04		400		
	non noble metal	chromium	7440-47-3	0.002	0.12		1199		
	non noble metal	copper	7440-50-8	0.570	39.79	39.96	397859	399538	
wire	noble metal	gold	7440-57-5	0.004	0.27	0.27	2739	2739	
	encapsulation	organic material	carbon black	1333-86-4	0.008	0.55		5458	
	plastics	epoxy resin	-	0.168	11.73		117347		
		inorganic material	silicondioxide	60676-86-0	0.607	42.30	54.58	422995	545800
	leadfinish	non noble metal	tin	7440-31-5	0.034	2.36	2.36	23644	23644
plating	noble metal	silver	7440-22-4	0.025	1.74	1.74	17374	17374	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com